MOSFET – Single, N-Channel with ESD Protection, Small Signal, SC-75 and SC-89 20 V, 915 mA

Features

- Low R_{DS(on)} Improving System Efficiency
- Low Threshold Voltage, 1.5 V Rated
- ESD Protected Gate
- NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- Pb-Free Packages are Available

Applications

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Portables like Cell Phones, PDAs, Digital Cameras, Pagers, etc.

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Paramet	Symbol	Value	Units		
Drain-to-Source Voltage			V _{DSS}	20	V
Gate-to-Source Voltage	V _{GS}	±6.0	V		
Continuous Drain	Steady T _A = 25°C		۱ _D	915	mA
Current (Note 1)	State	$T_A = 85^{\circ}C$		660	
Power Dissipation (Note 1)	Steady State		P _D	300	mW
Pulsed Drain Current	t _p =	=10 μs	I _{DM}	1.3	А
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C
Continuous Source Current (Body Diode)			۱ _S	280	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			Τ _L	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State (Note 1) SC-75 / SOT-416 SC-89	$R_{\theta JA}$	416 400	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on FR4 board using 1 in sq pad size

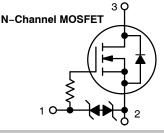
(Cu area = 1.127 in sq [1 oz] including traces).



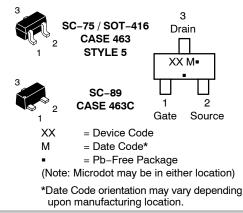
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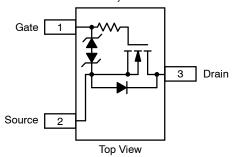
V _{(BR)DSS}	R _{DS(on)} TYP	I _D MAX
20 V	0.127 Ω @ 4.5 V	
	0.170 Ω @ 2.5 V	915 mA
	0.242 Ω @ 1.8 V	01011/
	0.500 Ω @ 1.5 V	



MARKING DIAGRAM & PIN ASSIGNMENT







ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

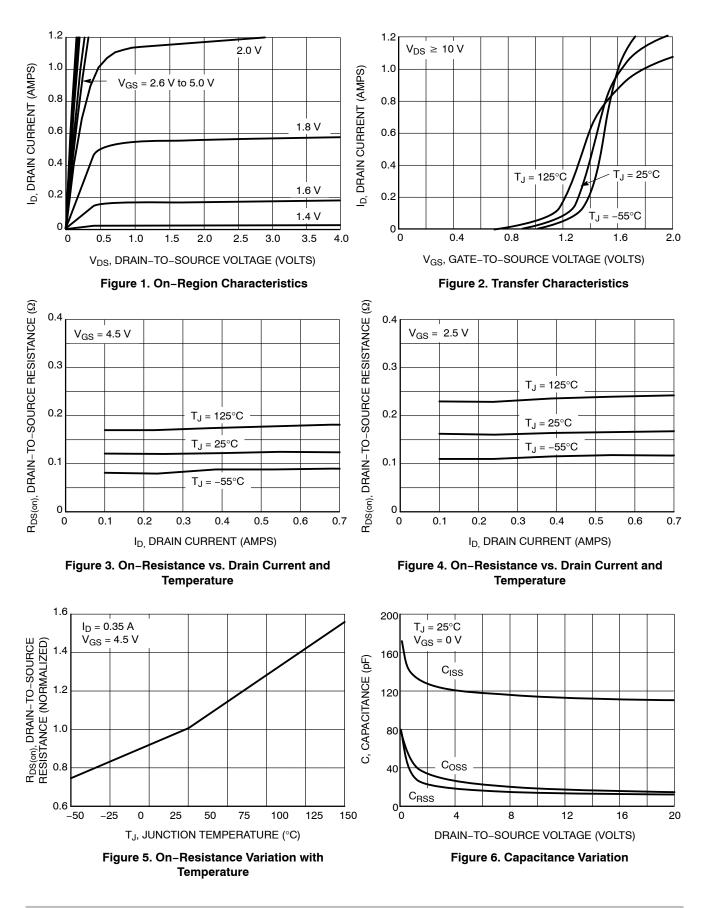
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Cond	lition	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \ \mu\text{A}$ 20		20	26		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				18.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _E	_{os} = 16 V			100	nA
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	_S = ±4.5 V			±1.0	μA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 250 μA	0.45	0.76	1.1	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-2.15		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 4.5 V, I _D	= 600 mA		127	230	mΩ
		V_{GS} = 2.5 V, I _D	= 500 mA		170	275	
		V _{GS} = 1.8 V, I _D = 350 mA			242	700	1
		V _{GS} = 1.5 V, I _[₀ = 40 mA		500	950	
Forward Transconductance	g fs	V_{DS} = 10 V, I_D	= 400 mA		1.4		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				110		pF
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 16 V			16		
Reverse Transfer Capacitance	C _{RSS}				12		
Total Gate Charge	Q _{G(TOT)}				1.82		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _I I _D = 0.2	_{DS} = 10 V,		0.2		
Gate-to-Source Charge	Q _{GS}	I _D = 0.2	2 A		0.3		
Gate-to-Drain Charge	Q _{GD}	ļ Ī			0.42		
SWITCHING CHARACTERISTICS (No	te 3)						
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 4.5 V, V_{DD} = 10 V, I_{D} = 0.2 A, R_{G} = 10 Ω			3.7		ns
Rise Time	t _r				4.4		
Turn-Off Delay Time	t _{d(OFF)}				25		
Fall Time	t _f				7.6		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.67	1.1	V
		I _S = 200 mA	T _J = 125°C		0.54		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2%.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL ELECTRICAL CHARACTERISTICS



TYPICAL ELECTRICAL CHARACTERISTICS

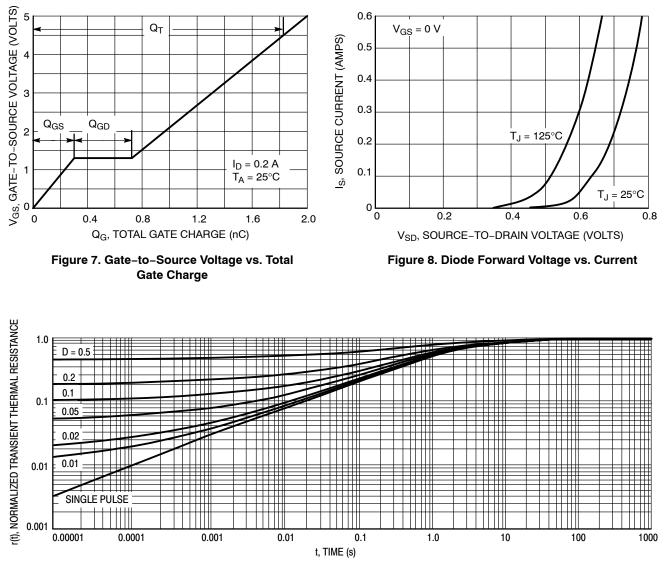


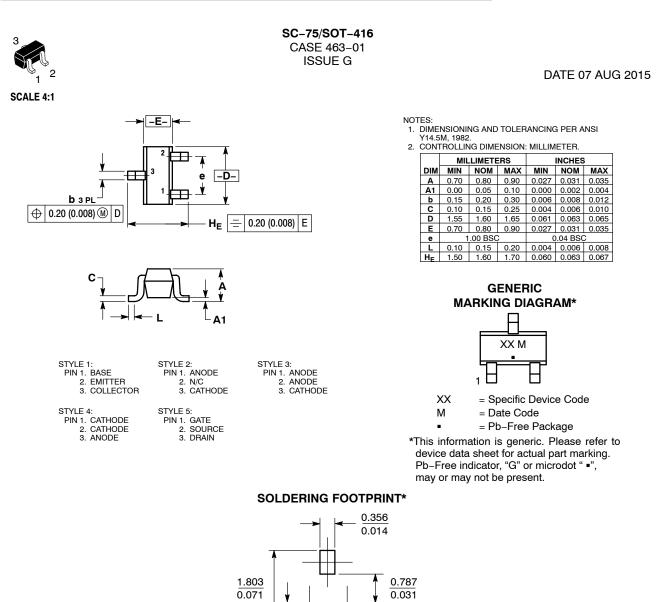
Figure 9. Normalized Thermal Response

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTA4153NT1	TR	SC-75 / SOT-416	3000 / Tape & Reel
NTA4153NT1G	TR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel
NTE4153NT1G	TP	SC-89 (Pb-Free)	3000 / Tape & Reel
NVA4153NT1G	VR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel
NVE4153NT1G	VP	SC–89 (Pb–Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

1.000

0.039

SCALE 10:1

mm

inches

0.508

0.020

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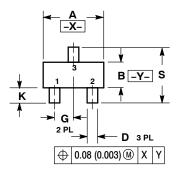
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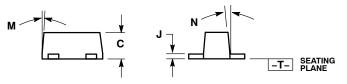
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SCALE 4:1





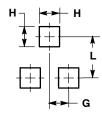
STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

STYLE 2: PIN 1. ANODE 2. N/C 3. CATHOD-Е

STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE



SC-89, 3 LEAD CASE 463C-03 **ISSUE C**



RECOMMENDED PATTERN OF SOLDER PADS

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS
- 2. OOKTIGETING DIMENSION INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.60	1.70	0.059	0.063	0.067	
В	0.75	0.85	0.95	0.030	0.034	0.040	
С	0.60	0.70	0.80	0.024	0.028	0.031	
D	0.23	0.28	0.33	0.009	0.011	0.013	
G	0.50 BSC			0.020 BSC			
Н	0.53 REF			0.021 REF			
J	0.10	0.15	0.20	0.004	0.006	0.008	
K	0.30	0.40	0.50	0.012	0.016	0.020	
L	1.10 REF			0.043 REF			
Μ			10			10	
Ν			10 -			10 -	
S	1.50	1.60	1.70	0.059	0.063	0.067	

GENERIC **MARKING DIAGRAM***



xx = Specific Device Code = Date Code D

*This information is generic. Please refer to device data sheet for actual part marking.

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